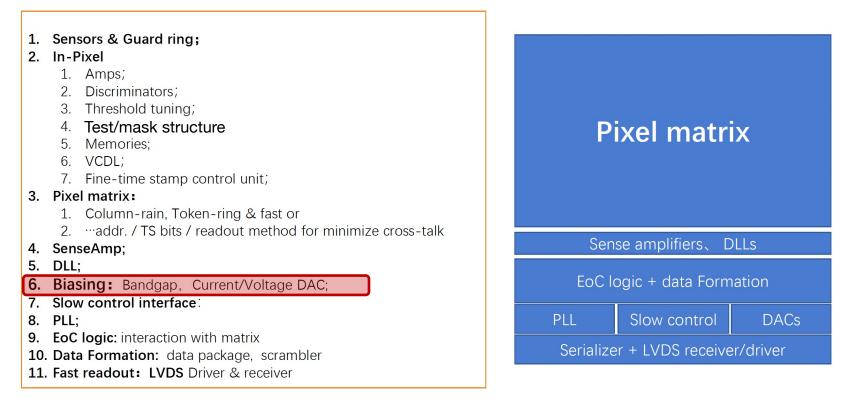
CEPC Silicon Tracker Progress Report (12)

Qi Yan on behalf of the Silicon Tracker Group Nov 19, 2024, IHEP

Upcoming MPW Submission Plan for HVCMOS Pixels

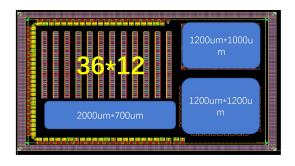
- Submission plan update for 2025:
 - Two MPW windows in the first half of 2025: January and April
 - Initial plan: 1 MPW to implement all periphery functions



- To demonstrate part of key performance by ref-TDR release (June 2025?):
 - 1st submission in January: all basic functions except DAC
 - 2nd submission in April or later 2025: DAC included, all other modules optimized

Preparation Towards Next Submission (COFFEE3 ...)

- 15 active designers:
 - preparation for some modules started right after COFFEE2
 - A few modules already in the layout phase
 - However, it remains an extremely challenging task



General layout planning Pixel size: 34 μm×144 μm MPW size: 3 mm×4 mm



Staff and students from IHEP, NWPU, DMU, SDU, NJU, ...